



2SJ401

Unit: mm

1.32

10.6 MAX

12.6 MIN.

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type ($L^2 - \pi - MOSV$)

2SJ401

DC-DC Converter, Relay Drive and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON resistance $: RDS (ON) = 33 m\Omega (typ.)$
- High forward transfer admittance $: |Y_{fs}| = 20 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = -100 \ \mu A \ (max) \ (V_{DS} = -60 \ V)$
- Enhancement mode : $V_{th} = -0.8 \sim -2.0 \text{ V} (V_{DS} = -10 \text{ V}, \text{ Ip} = -1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	-60	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	-60	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	Ι _D	-20	А	
	Pulse(Note 1)	IDP	-80	А	
Drain power dissipation (Tc = 25°C)		PD	100	W	
Single pulse avalanche energy (Note 2)		E _{AS}	800	mJ	
Avalanche current		I _{AR}	-20	А	
Repetitive avalenche energy (Note 3)		E _{AR}	10	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.25	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	83.3	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = -50 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.44 mH, $R_G = 25 \Omega$, $I_{AR} = -20 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

2.54±0.25 2.54±0.25 2.54±0.25 2.54±0.25 1. GATE 2. DRAIN (HEAT SINK) 3. SOURCE

2-10S1B

10.3MAX

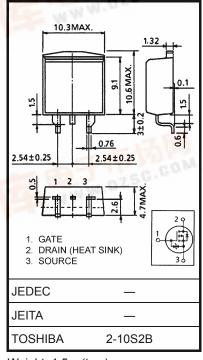
SMAX

1.6 MAX. 0.76

JEITA

TOSHIBA

Weight: 1.5 g (typ.)



Weight: 1.5 g (typ.)

his transistor is an electrostatic-sensitive device. Please handle with caution.

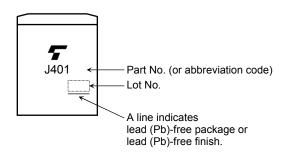
Electrical Characteristics (Ta = 25°C)

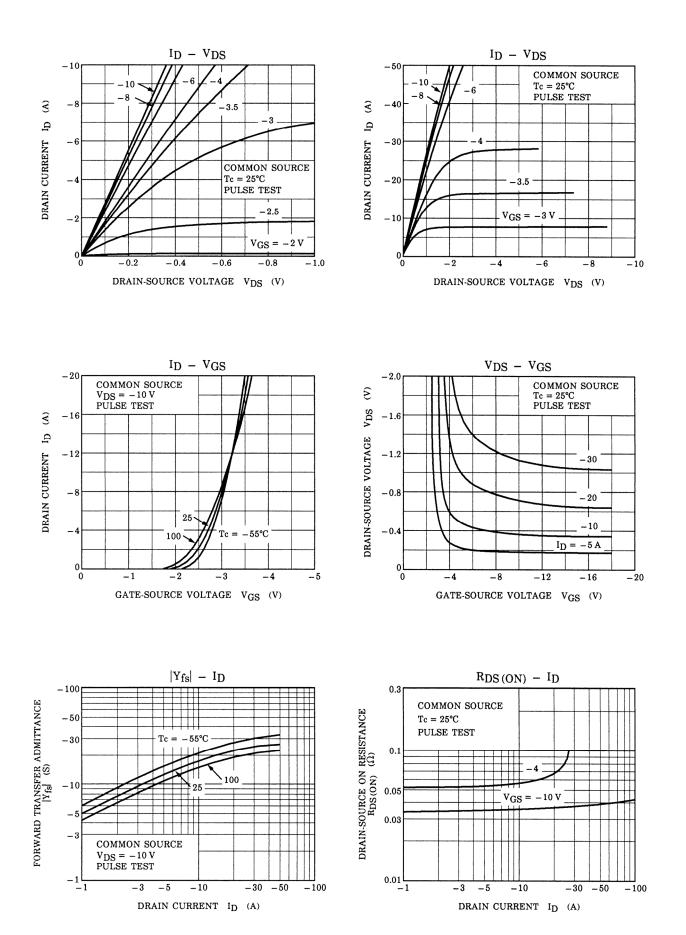
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V		_	±10	μA
Drain cut-off current		I _{DSS}	$V_{DS} = -60 V, V_{GS} = 0 V$		_	-100	μA
Drain-source bi	reakdown voltage	V (BR) DSS	I _D = −10 mA, V _{GS} = 0 V	-60	_	_	V
Gate threshold	voltage	V _{th}	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = -4 V, I _D = -10 A	_	50	90	
			V _{GS} = -10 V, I _D = -10 A	_	33	45	mΩ
Forward transfe	r admittance	Y _{fs}	V _{DS} = -10 V, I _D = -10 A	10	20	_	S
Input capacitand	ce	C _{iss}		_	2800	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = −10 V, V _{GS} = 0 V, f = 1 MHz	_	450	_	pF
Output capacitance		Coss			1300	_	
Switching time	Rise time	tr	$V_{GS} \xrightarrow{0V} \overbrace{I_{D}}^{I_{D}=-10A} V_{OUT}$ $V_{OUT} \xrightarrow{R_{L}=} 3\Omega$ $V_{DD}=-30V$ $Duty \leq 1\%, t_{W}=10\mu s$	_	15	-	
	Turn-on time	t _{on}		_	35	_	20
	Fall time	t _f		_	25	-	ns
	Turn-off time	toff		_	120	-	
Total gate charge (Gate-source plus gate-drain)		Qg		_	90	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ −48 V, V _{GS} = −10 V, I _D = −20 A		65	_	nC
Gate-drain ("miller") charge		Q _{gd}			25	_	

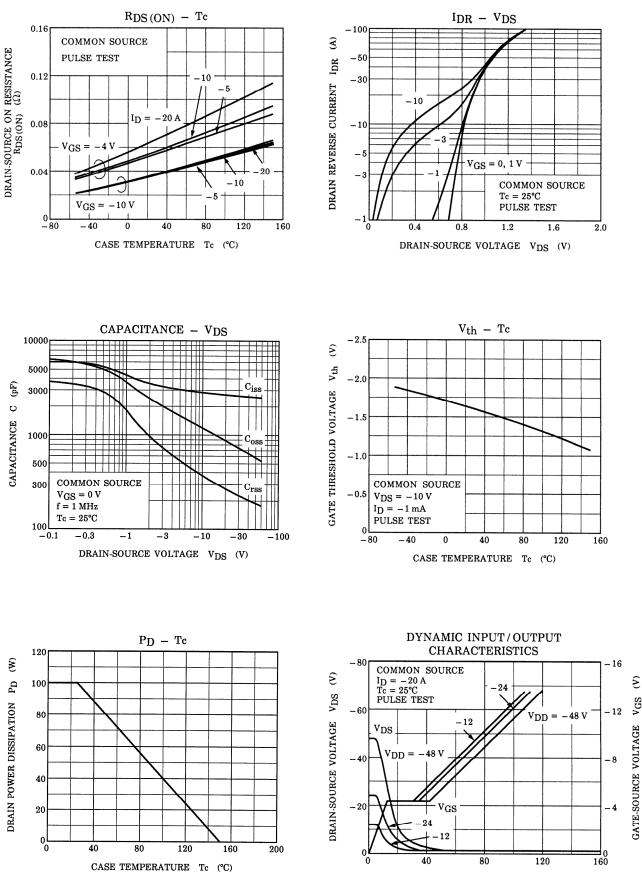
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	-20	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	-80	А
Forward voltage (diode)	V _{DSF}	I _{DR} = -20 A, V _{GS} = 0 V	_	_	1.7	V
Reverse recovery time	t _{rr}	I _{DR} = -20 A, V _{GS} = 0 V	_	75		ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 50 A / µs	_	83	_	nC

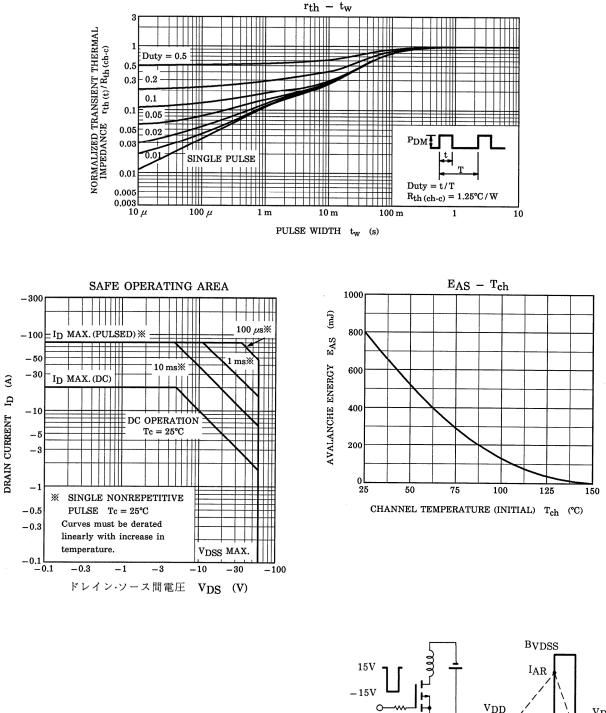
Marking

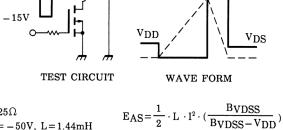






TOTAL GATE CHARGE Qg (nC)





 $R_G = 25\Omega$ $V_{DD} = -50V, L = 1.44mH$

RESTRICTIONS ON PRODUCT USE

Handbook" etc.

20070701-EN

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